

IN THE CLAIMS:

Please cancel claims 23 and 25 without prejudice.

- sub D3
C1
- 1 28. A substrate contact for forming a non-reflow electrical contact with a
2 solder ball, comprising:
3 a recess defined in a substrate by at least one surface extending into said substrate;
4 and
5 a conductive material layered over said recess forming a void therebetween.

REMARKS

This Amendment is in response to the Official Action mailed June 21, 2001. The Office Action was in response to a Response After Final Rejection. However, the present Office Action has stated that it is a non-final rejection. Thus, although not stated by the present Office Action, it is assumed that the Applicants arguments were found persuasive and that the March 22, 2001 Final Rejection has been withdrawn.

Claims 1, 2, 4-7, 12-16 and 28-33 remain in the application. Claims 23 and 25 have been canceled without prejudice. Claim 28 has been amended to more clearly define the present invention. No new subject matter has been added with this amendment.